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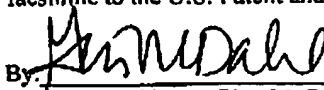
S/N 10/775,656

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Yamashita et al	Examiner:	Dinh
Serial No.:	10/775,656	Group Art Unit:	2841
Filed:	February 9, 2004	Docket No.:	10873.1397US01
Title:	ELECTRONIC COMPONENT BUILT-IN MODULE AND METHOD OF MANUFACTURING THE SAME		

CERTIFICATE UNDER 37 CFR 1.6(d):

I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on August 7, 2006.

By: 

Name: Gina M. Dahl

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Dear Sir:

Applicants request favorable reconsideration of this application in view of the following remarks.

Claims 1-17 were rejected as being unpatentable over Nakatani (US 6,038,133) in view of Ozawa (US 5,172,304). Applicants traverse this rejection.

Claim 1 requires a pair of opposed circuit substrates with an insulating layer disposed therebetween. An inner via connecting wiring patterns on the opposed substrates is provided in the insulating layer. An electronic component is embedded in the insulating layers. The substrates include an insulating base material containing a resin, and the insulating layer contains an inorganic filler and a resin composition containing a thermosetting resin. The glass transition temperature of the resin composition contained in the insulating layer is higher than the glass